



Material Content Data Sheet



Sales Product Name	TLE42994GM			Issued	2. May 2017			
MA#	MA001355250							
Package	PG-DSO-14-30			Weight*	143.13 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	2.09	2.09	20927	20927
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		422	
	non noble metal	iron	7439-89-6	1.207	0.84		8432	
wire	non noble metal	copper	7440-50-8	49.007	34.24	35.13	342389	351348
	noble metal	gold	7440-57-5	0.190	0.13	0.13	1325	1325
	encapsulation	organic material	carbon black	1333-86-4	0.172	0.12		1201
	plastics	epoxy resin	-	7.910	5.53		55265	
	inorganic material	silicondioxide	60676-86-0	77.899	54.43	60.08	544245	600711
leadfinish	non noble metal	tin	7440-31-5	1.226	0.86	0.86	8566	8566
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7195	7195
glue	plastics	acrylic resin	-	0.313	0.22		2184	
	noble metal	silver	7440-22-4	1.108	0.77	0.99	7744	9928
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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